

**ABSTRACT OF THE DISCLOSURE**

A method of manufacturing a circuit board by forming a circuit pattern in a short process and capable of performing pattern transfer with stability. The manufacturing method includes a step of superposing on a carrier a resist layer in which a circuit pattern is formed and which is formed of a conductor or an insulator, a step of filling the circuit pattern with an electroconductive material, a step of removing the resist layer from the carrier, and a step of transferring the electroconductive material filled in the circuit pattern into an electrical insulating material.